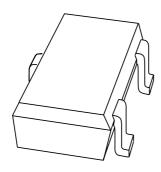
## DISCRETE SEMICONDUCTORS

## DATA SHEET



# **BAP51-04W**General purpose PIN diode

Preliminary specification

2002 Feb 19





## General purpose PIN diode

## **BAP51-04W**

#### **FEATURES**

- Two elements in series configuration in a small SMD plastic package
- Low diode capacitance
- Low diode forward resistance.

## **APPLICATIONS**

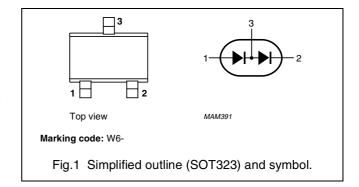
· General RF applications.

## **DESCRIPTION**

Two planar PIN diodes in series configuration in a SOT323 small SMD plastic package.

#### **PINNING**

PIN	DESCRIPTION
1	anode
2	cathode
3	common connection



## **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V <sub>R</sub>	continuous reverse voltage		_	50	V
I <sub>F</sub>	continuous forward current		_	50	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> = 90 °C	_	240	mW
T <sub>stg</sub>	storage temperature		<del>-</del> 65	+150	°C
Tj	junction temperature		-65	+150	°C

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## General purpose PIN diode

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## **ELECTRICAL CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	ER CONDITIONS		TYP.	MAX.	UNIT
Per diode				'	'	
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA	_	0.95	1.1	V
V <sub>R</sub>	reverse voltage	I <sub>R</sub> = 10 μA	50	_	_	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V	_	_	100	nA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0; f = 1 MHz	_	0.4	_	pF
		V <sub>R</sub> = 1 V; f = 1 MHz	_	0.3	0.55	pF
		V <sub>R</sub> = 5 V; f = 1 MHz	_	0.2	0.35	pF
r <sub>D</sub>	diode forward resistance	I <sub>F</sub> = 0.5 mA; f = 100 MHz; note 1	_	5.5	9	Ω
		I <sub>F</sub> = 1 mA; f = 100 MHz; note 1	_	3.6	6.5	Ω
		I <sub>F</sub> = 10 mA; f = 100 MHz; note 1	_	1.5	2.5	Ω
$\tau_{L}$	charge carrier life time	when switched from $I_F$ = 10 mA to $I_R$ = 6 mA; $R_L$ = 100 $\Omega$ ; measured at $I_R$ = 3 mA	_	550	_	ns
L <sub>S</sub>	series inductance	I <sub>F</sub> = 10 mA; f = 100 MHz	_	1.6	_	nH

## Note

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	250	K/W

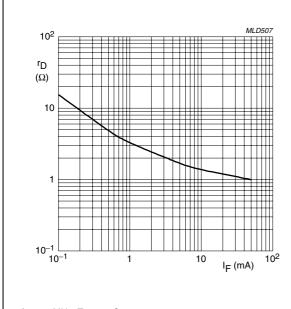
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<sup>1.</sup> Guaranteed on AQL basis: inspection level S4, AQL 1.0.

## General purpose PIN diode

**BAP51-04W** 

#### **GRAPHICAL DATA**



f = 100 MHz;  $T_i = 25 \,^{\circ}\text{C}$ .

Fig.2 Forward resistance as a function of forward current; typical values.

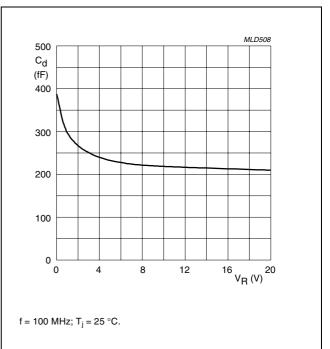
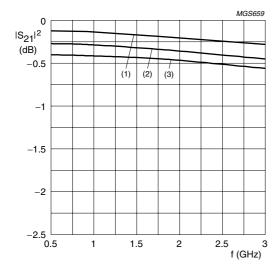


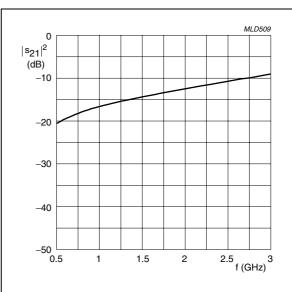
Fig.3 Diode capacitance as a function of reverse voltage; typical values.



- (1)  $I_F = 10 \text{ mA}.$
- (2)  $I_F = 1 \text{ mA}$
- (3)  $I_F = 0.5 \text{ mA}$

Diode inserted in series with a 50  $\,\Omega$  stripline circuit and biased via the analyzer Tee network. T  $_{amb}$  = 25  $^{\circ}C$  .

Fig.4 Insertion loss  $(|s_{21}|^2)$  of the diode as a function of frequency; typical values.



Diode zero biased and inserted in series with a 50  $\Omega$  stripline circuit.  $T_{amb}$  = 25  $^{\circ}C.$ 

Fig.5 Isolation ( $|s_{21}|^2$ ) of the diode as a function of frequency; typical values.

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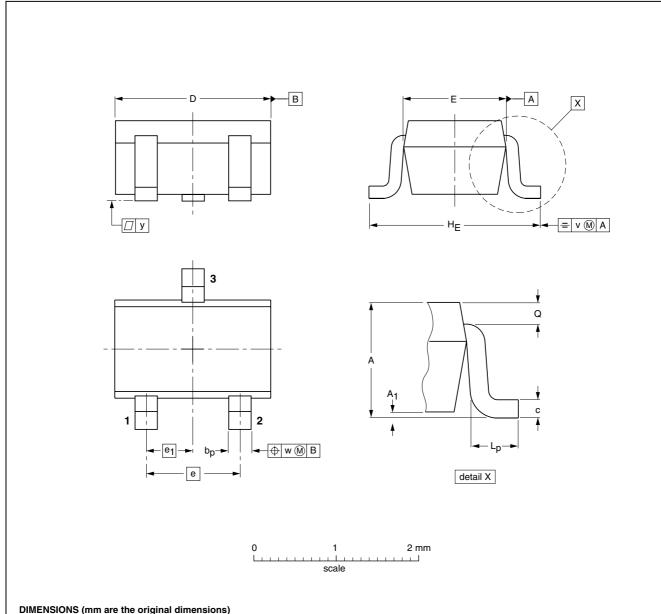
## General purpose PIN diode

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## **PACKAGE OUTLINE**

## Plastic surface mounted package; 3 leads

**SOT323** 



DIMENSIONS (m	ım are t	he original	dimensions)

ı	JNIT	A	A <sub>1</sub> max	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	V	w
	mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT323			SC-70			97-02-28

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## General purpose PIN diode

**BAP51-04W** 

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DATA SHEET STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
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